

/ Descriptions

WR0<50 P M M E QSQ æ M y s ll 1 Silicon NPN transistor in a TO-92LM Plastic Package.

/ Features

$$M \otimes_R A \cong \bigoplus_{i=1}^n M \otimes_R A_i$$

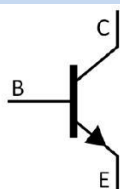
High breakdown voltage, low output capacitance, high transition frequency.

/ Applications

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B/W TV video output, high voltage switching application.

/ Equivalent Circuit



/ Pinning

PIN1 $\times$ BasePIN 2 χ Collector

PIN 3 $\times$ Emitter

/ h_{FE} Classifications & Marking

h _{FE} Classifications Symbol	O	Y
h _{FE} Range	70~140	120~240

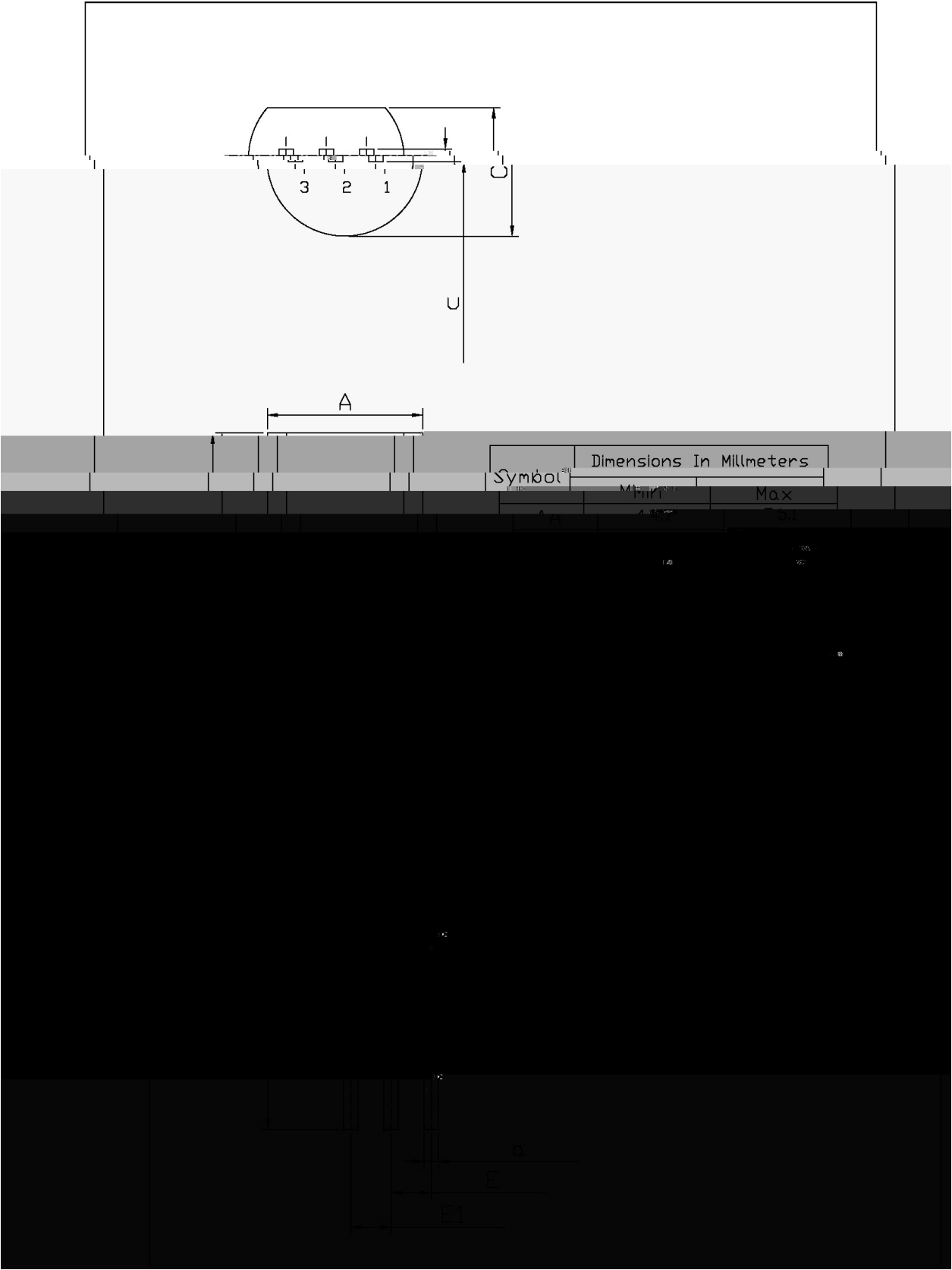
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	200	V
Collector to Emitter Voltage	V_{CEO}	150	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	50	mA
Emitter Current - Continuous	I_E	-50	mA
Collector Power Dissipation	P_C	1.0	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=200V$ $I_E=0$			0.1	A
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=5.0V$ $I_C=0$			0.1	A
DC Current Gain	h_{FE}	$V_{CE}=5.0V$ $I_C=10mA$	70		240	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=10mA$ $I_B=1.0mA$			0.5	V
Base to Emitter Voltage	$V_{BE(sat)}$	$I_C=10mA$ $I_B=1.0mA$			1.0	V
Transition Frequency	f_T	$V_{CE}=30V$ $I_C=10mA$		120		MHz
Collector output capacitance	C_{ob}	V				

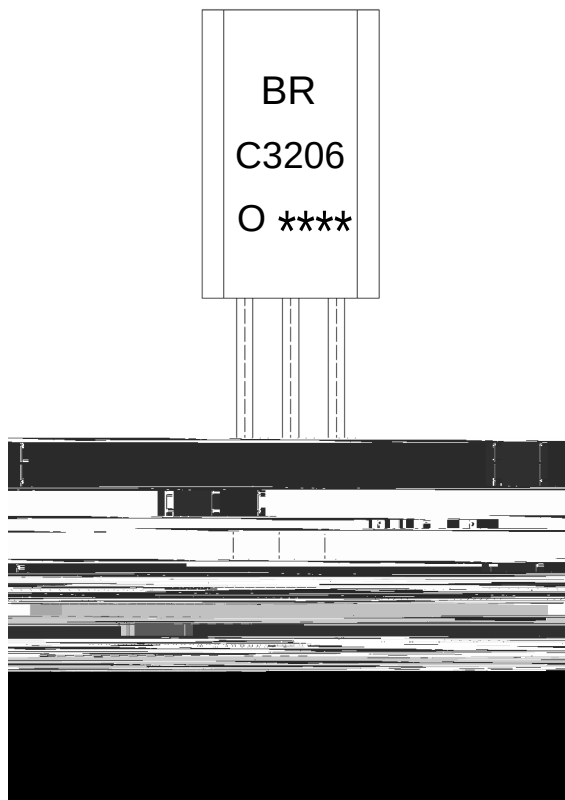
/ Package Dimensions

T0-92LM

Unit: mm



/ Marking Instructions



б " X

EU: Խ Յ Մ Ո

F6539: Խ Յ Ն Ո

R: Խ k_{1H} 6 Ո

---- X Խ Ի Բ ը Ն Ո Ի Զ Ի Բ ը Ն Ս Ր

Note:

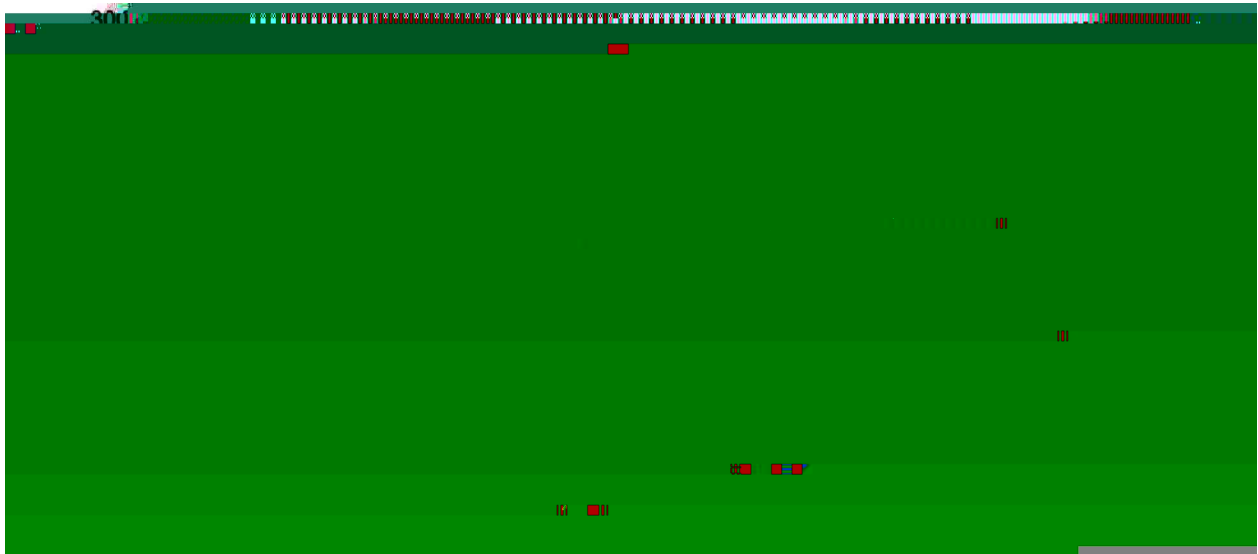
BR: Company Code.

C3206: Product Type.

O: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



б " χ

1. 1. 25~150 °C, Time: 60~90sec;
2. 2. 255 °C, Duration: 5~0.5sec;
3. 3. Cooling Speed: 2~10 °C/sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 255 °C, Duration: 5~0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

□ °C 270 °C ± 5 °C °C 10 °C ± 1 sec. Temp.: 270 °C ± 5 °C Time: 10 °C ± 1 sec

/ Packaging SPEC.

°C °C °C / BULK

Package Type	Units	Dimension	(unit mm3) 10
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